



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Applicant of  
Khandros et al.

Group Art Unit: 2815

Continued Prosecution Application  
of Serial No. 08/984,615

Examiner: S. Clark

Filed: December 3, 1997

Date: September 10, 1998

For: **SEMICONDUCTOR CHIP PACKAGE  
WITH CENTER CONTACTS**

Batch No. F86

Assistant Commissioner For Patents  
Box Patent Application  
Washington, D.C. 20231

*Pre-Amended*  
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SEP 18 1998  
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**PRELIMINARY AMENDMENT**

Sir:

Prior to calculating the filing fee in the Continued Prosecution Application filed contemporaneously herewith, please amend the application as follows:

**In the Claims:**

Insert new claims 71-76 as follows:

*71.11* A chip assembly as claimed in claim ~~61~~<sup>1</sup> wherein the contact leads include wire bonds.

*72.12* A semiconductor chip assembly comprising:

(a) a semiconductor chip having a front surface defining the top of the chip, said front surface including a central region and a peripheral region surrounding said central region, whereby said central region is disposed inwardly of said peripheral region, said chip having central contacts disposed in said central region of said front surface;

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